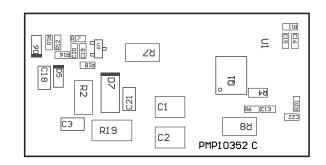


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE		BOARD #: PMP10352	REV: C	SVN REV: Not In VersionControl	
IGNORE ->	Top Overlay				
PLOT NAME =	Top Assembly Drawing	GENERATED : 6/27/2	2017 4: 32:14	PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP10352	REV: C	SUN REU:	Not In VersionControl	
	IGNORE -> ų		er l ay	Bottom Overl	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 6/27/2	2017 4: 32: 15	PM	TEXAS INSTRUMENTS	

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